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2 3. (Amended) A method of bonding [solder] balls of solder to
bond pads on a substrate comprising:

3 placing at least portions of a plurality of [solder] balls of solder
4 within a frame and in registered alignment with individual bond pads
5 over a substrate; and

6 while the ball portions are within the frame, exposing the balls to
7 bonding conditions effective to bond the balls with their associated bond
8 pads.

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10 Cancel claims 4 and 5.

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12 6. 5 (Amended) The method of [bonding solder balls of] claim
13 3, wherein [said] exposing comprises laser bonding the balls with their
14 associated bond pads.

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16 Cancel claim 7.

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18 4 8. 6 (Amended) The method [of bonding solder balls] of claim
19 3, wherein [said] exposing comprises laser bonding the balls with their
20 associated bond pads by fixing the position of a laser beam and moving
21 the frame relative to the laser beam from ball-to-ball.

22
23 Cancel claims 9 and 10.

1 11. (Amended) The method of [bonding solder balls of] claim

2 3, wherein:

3 4 [said] placing comprises placing individual [solder] balls within
4 individual holes within the frame; and

5 [said] exposing [of the balls] comprises reflowing the [solder] balls
6 while the balls are within their individual holes, and further comprising,
7 after [said] reflowing, removing the frame from around the reflowed
8 balls.

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10 12. (Amended) The method of [bonding solder balls of] claim 3,
11 wherein [said] placing comprises placing [said] ~~the~~ ball portions on
12 fluxless bond pad surfaces.

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14 13. (Amended) A method of bonding [solder] balls of solder to
15 bond pads on a substrate comprising:

16 providing a frame having a plurality of holes sized to receive
17 individual solder balls;

18 delivering individual balls of solder into the holes from over the
19 frame;

20 placing the balls into registered alignment, while the balls are in
21 the holes, with a plurality of individual bond pads over a substrate; and
22 bonding the balls with their individual associated bond pads.
23

1 Cancel claims 14-19.

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3 ~~20.~~ ⁹ (Amended) The method of claim ~~13~~ ⁸, wherein [the] bonding
4 [of the balls] comprises laser bonding the balls with their individual
5 associated bond pads.
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7 Cancel claim 21.

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9 ~~22.~~ ¹⁰ (Amended) The method of claim ~~13~~ ⁸, wherein [the] bonding
10 [of the balls] comprises laser bonding the balls with their individual
11 associated bond pads by fixing the position of a laser beam and moving
12 the frame relative to the laser beam from ball-to-ball to effectuate the
13 bonding.
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15 Cancel claim 25.
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27. (Amended) A method of bonding a [solder] ball of solder
to a bond pad on a substrate comprising:

providing a frame having a hole;

providing a [solder] ball of solder having an outer surface;

retaining the [solder] ball of solder within the hole in an ambient
processing environment which is generally uniform over the entirety of
the ball's outer surface; and

while the [solder] ball of solder is within the hole, bonding the
[solder] ball of solder with an associated bond pad on a substrate.

Cancel claim 28.

30. (Amended) The method of claim ~~27~~, wherein [the] bonding
[of the solder ball] comprises laser bonding [said] the ball.

31. (Amended) A method of bonding [solder] balls of solder to bond pads on a substrate comprising:

providing a surface having a plurality of holes therein;

providing a plurality of [solder] balls of solder over the surface;

depositing some of the [solder] balls of solder into at least some of the holes; and

bonding the [solder] balls of solder which were deposited into the holes to individual associated bond pads positioned on a substrate proximate the holes.

Cancel claims 32-35.

36. (Amended) The method of claim 31, wherein [the] bonding [of the balls] comprises laser-bonding each ball to (an individual bond pad.)

37. (Amended) The method of claim 31, wherein [the] bonding [of the balls] comprises laser-bonding each ball to (an individual bond pad) by fixing the position of a laser beam and moving each ball into the path of the laser beam.

Cancel claims 38-40.

41. (Amended) [The method of claim 39] A method of bonding
balls of solder to bond pads on a substrate comprising:
providing a surface having a plurality of holes therein;
providing more balls of solder than there are holes over the
surface;
moving the plurality of balls and the surface relative to one
another effective to deposit one ball of solder into each hole;
removing excess balls of solder from over the surface; and
bonding the balls which were deposited into the holes to individual
bond pads positioned on a substrate proximate the holes, wherein [the]
bonding [of the balls] comprises laser bonding the balls by moving each
ball into the path of a laser beam.